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GROUP
281+ 2824

Div. U.S. PATENT DOCUMENTS Oct. 27/2003

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
AA						
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FOREIGN PATENT DOCUMENTS

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						Yes	No
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AO							
AP							
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

BEO	AU	"Ultra Thin Electronics for Space Applications", 2001 Electronic Components and Technology Conference, 2001 IEEE
BEO	AV	"Copper Wafer Bonding"; A. Fan, A. Rahman, and R. Reif; Electrochemical and Solid-State Letters, 2 (10)-534-536 (1999)
BEO	AW	"Face to Face Wafer Bonding for 3D Chip Stack Fabrication to Shorten Wire Lengths", June 27-29, 2000 VMIC Conference 2000 IMIC - 200/00/0090(c)
BEO	AX	"InterChip Via Technology for Vertical System Integration", Fraunhofer Institute for Reliability and Microintegration, Munich, Germany; Infineon Technologies AG, Munich, Germany; 2001 IEEE
	AY	
	AZ	

Examiner

Date Considered

6.23.04

Beth E. Owens